

IN THE CLAIMS

Please amend claims 1, 13, 17 and 21 and cancel claims 4 and 8 as shown below.

Claim 1 (Currently Amended) A gradient coil assembly for use in an MRI device, comprising:
 a gradient tube extending along an axis, the tube including first and second gradient coils and a conductive compound disposed between the first and second gradient coils, the conductive compound being a glue, and a chemical hardening compound disposed in the glue, and having a plurality of conductive particles disposed substantially uniformly within the glue, at least a portion of the plurality of conductive particles being in a range of 1-10 μ m in diameter, a volume percentage of the plurality of conductive particles is 0.1% or less of a volume of the conductive compound ~~the plurality of conductive particles configured to limit~~ such that a current flowing through the conductive compound is limited to less than 10 microamps to reduce electrostatic discharges in the glue.

Claim 2 (Previously Presented): The gradient coil assembly of claim 1 wherein the glue comprises an epoxy resin.

Claim 3 (Previously Presented): The gradient coil assembly of claim 1 wherein the conductive particles comprise carbon particles.

Claim 4 (Cancelled).

Claim 5 (Original): The gradient coil assembly of claim 2 wherein the epoxy resin comprises a bisphenol-A resin.

Claim 6 (Previously Presented): The gradient coil assembly of claim 1 wherein the glue comprises a polyester resin.

Claim 7 (Original): The gradient coil assembly of claim 6 wherein the conductive particles comprise one of carbon particles, silver particles, copper particles, and gold particles.

Claim 8 (Cancelled).

Claim 9 (Cancelled).

Claim 10 (Cancelled).

Claim 11 (Cancelled).

Claim 12 (Previously Presented): A gradient coil assembly for use in an MRI device, comprising:

a gradient tube extending along an axis, the tube including first and second gradient coils and a potting compound layer disposed between the first and second gradient coils, the potting compound layer having a plurality of conductive particles configured to limit a current flowing through the potting compound layer to less than a predetermined current value to reduce electrostatic discharges in the potting compound layer, the plurality of conductive particles being at least one of silver particles and gold particles.

Claim 13 (Currently Amended): A method for assembling a gradient coil assembly, comprising:

disposing a first gradient coil on a first gradient tube; and

disposing a conductive compound between the first gradient coil and a second gradient coil, the conductive compound being a glue having a plurality of conductive particles therein, at least a portion of the plurality of conductive particles being in a range of 1-10 μ m in diameter, a volume percentage of the plurality of conductive particles is 0.1% or less of a volume of the conductive compound ~~the plurality of conductive particles configured to limit~~ such that a current flowing through the conductive compound is limited to less than 10 microamps ~~a predetermined value~~ to reduce electrostatic discharges in the glue, ~~the conductive compound further having a chemical hardening compound therein.~~

Claim 14 (Previously Presented): The method of claim 13 wherein the disposing the conductive compound includes vacuum impregnating the conductive compound between the first and second gradient coils.

Claim 15 (Previously Presented): The method of claim 13 wherein the glue comprises an epoxy resin.

Claim 16 (Cancelled).

Claim 17 (Currently Amended): The method of claim 15 wherein the conductive particles comprise one of carbon particles, silver particles, ~~copper particles~~, and gold particles.

Claim 18 (Previously Presented): The method of claim 13 wherein the glue comprises a polyester resin.

Claim 19 (Cancelled).

Claim 20 (Cancelled).

Claim 21 (Currently Amended): A gradient coil assembly for use in an MRI device, comprising:
a gradient tube extending along an axis, the tube including first and second gradient coils and a conductive compound disposed between the first and second gradient coils, the conductive compound being a glue having a plurality of conductive particles dispersed substantially uniformly within the glue, at least a portion of the plurality of conductive particles being in a range of 1-10 μ m in diameter, a volume percentage of the plurality of conductive particles being within a predetermined volume percentage range of the conductive compound such that the plurality of conductive particles configured to limit a current flowing through the conductive compound is limited to less than 10 microamps to reduce electrostatic discharges in the glue, ~~the conductive particles being one of silver particles, copper particles, and gold particles.~~

Claim 22 (Previously Presented): The gradient coil assembly of claim 21 wherein the glue comprises an epoxy resin.

Claim 23 (Previously Presented): The gradient coil assembly of claim 22 wherein the epoxy resin comprises a bisphenol-A resin.

Claim 24 (Previously Presented): The gradient coil assembly of claim 21 wherein the glue comprises a polyester resin.